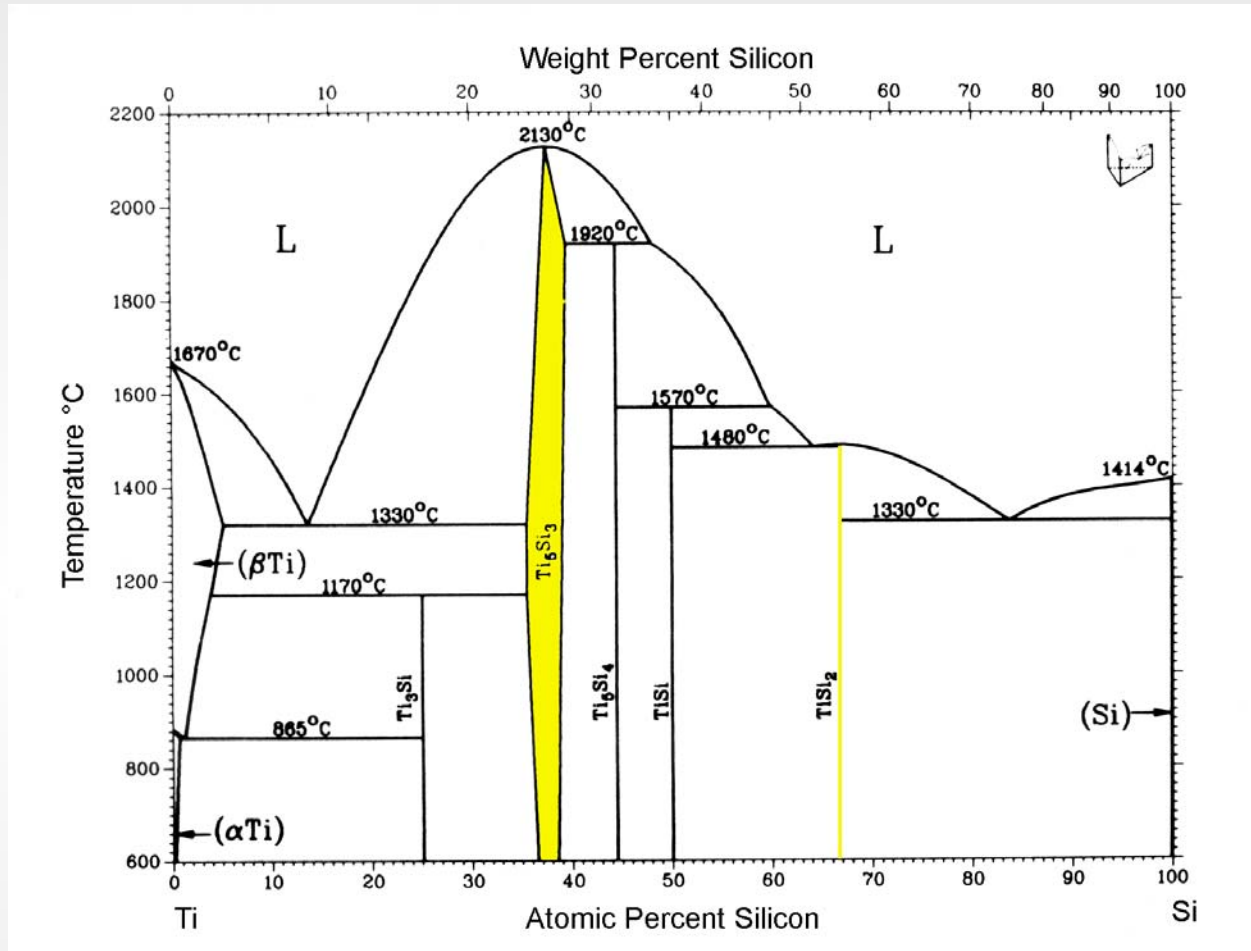




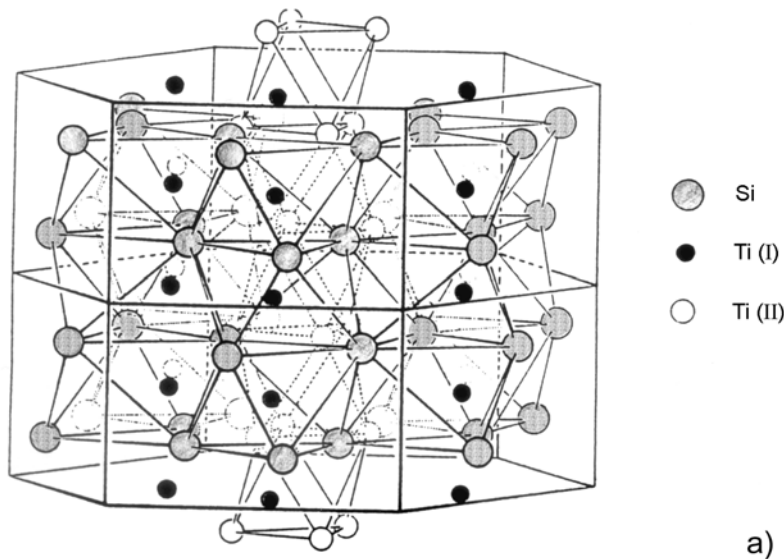
STRUCTURES AND PROPERTIES OF THE REFRACTORY SILICIDES Ti_5Si_3 AND TiSi_2 AND Ti-Si-(Al) EUTECTIC ALLOYS

- ⊕ Introduction
 - ⊕ Constitution of the binary phase diagram TiSi
 - ⊕ Intermetallic compounds Ti_5Si_3 and TiSi_2
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 - elastic moduli E, G, K
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 - ✧ Physical properties
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 - ✧ Mechanical properties
 - yield stress
 - fracture toughness
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Equilibrium phase diagram of the binary Ti-Si system



Crystal structures of the intermetallic and compounds.

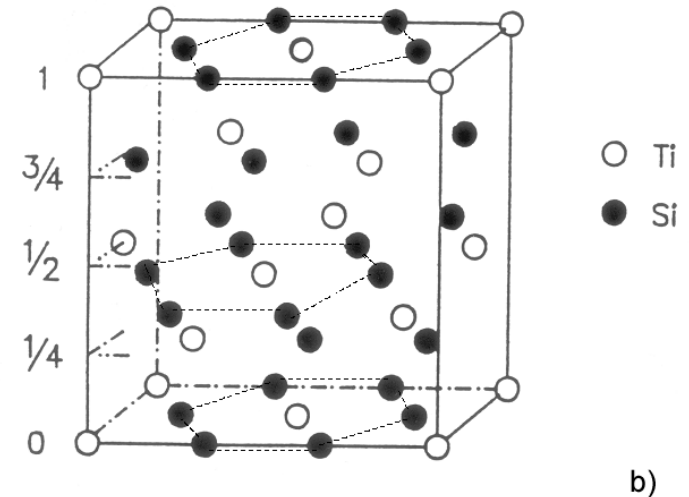
complex hexagonal $D8_8$

lattice parameters

$a = 0.514 \text{ nm}$

$c = 0.744 \text{ nm}$

$N = 16$ per unit cell



orthorhombic $C 54$

lattice parameters

$a = 0.8267 \text{ nm}$

$b = 0.4800 \text{ nm}$

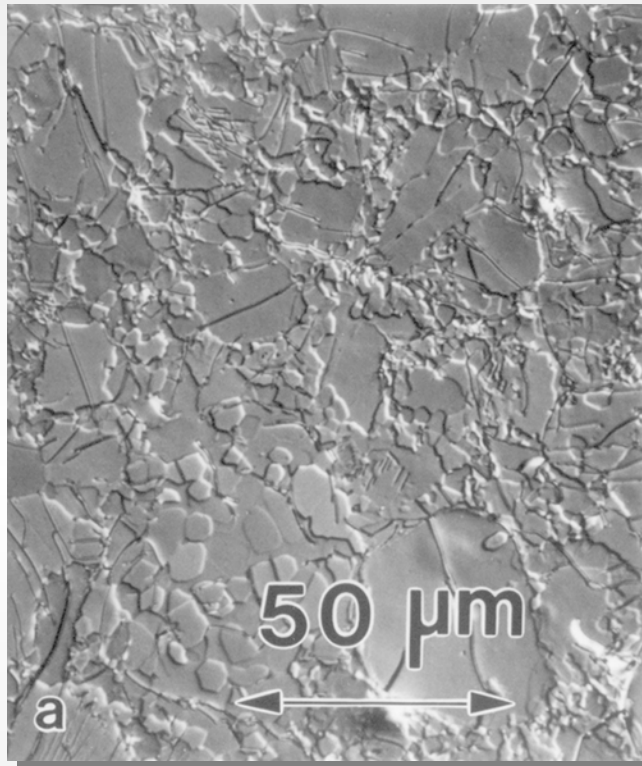
$c = 0.855 \text{ nm}$

$N = 24$ per unit cell

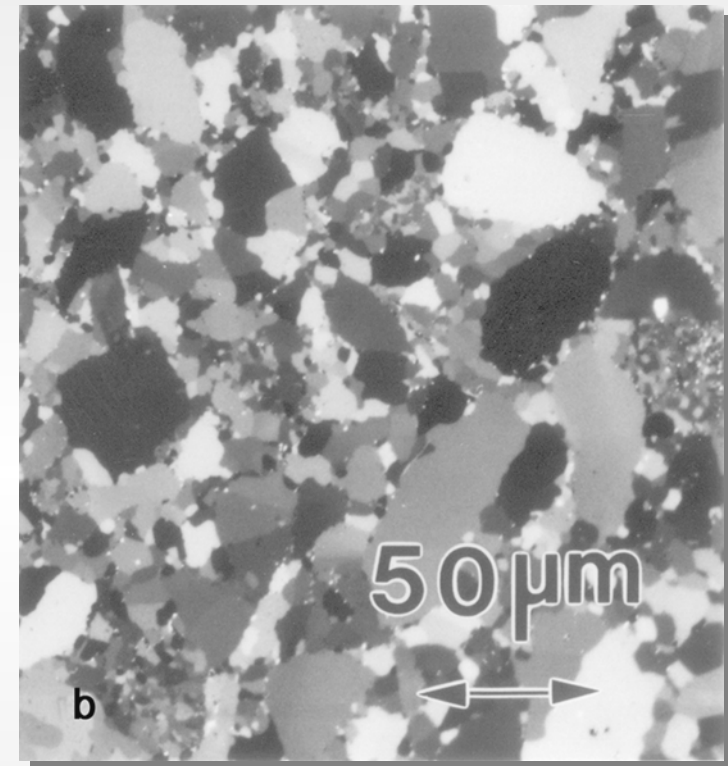


	binding energy (kJ/mole)	melting temperature (K)	Vickers' hardness (load : 1kp) (HV1)
Ti₅Si₃	- 1095 ± 40	2403	970 ± 20
TiSi₂	- 687,5 ± 25	1753	870 ± 15

Relation between binding energy, melting temperature and Vickers' hardness

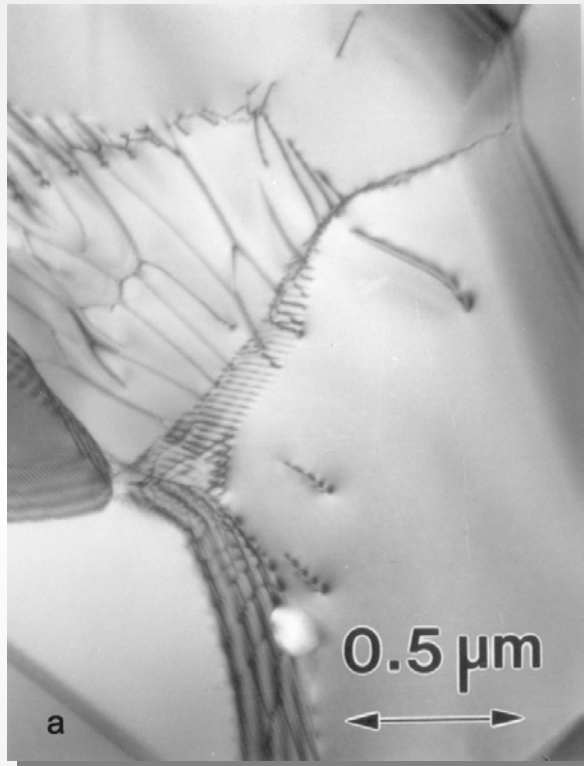


Ti_5Si_3

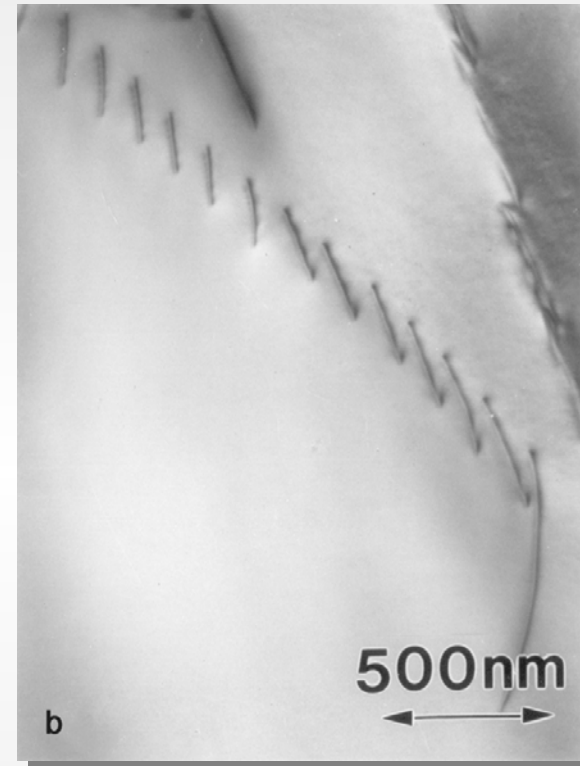


TiSi_2

Optical micrographs of as compacted compounds

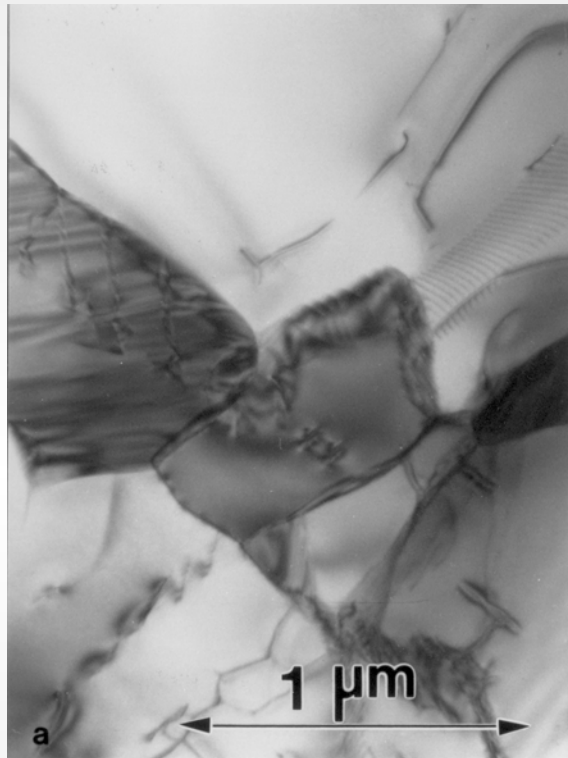


Ti_5Si_3

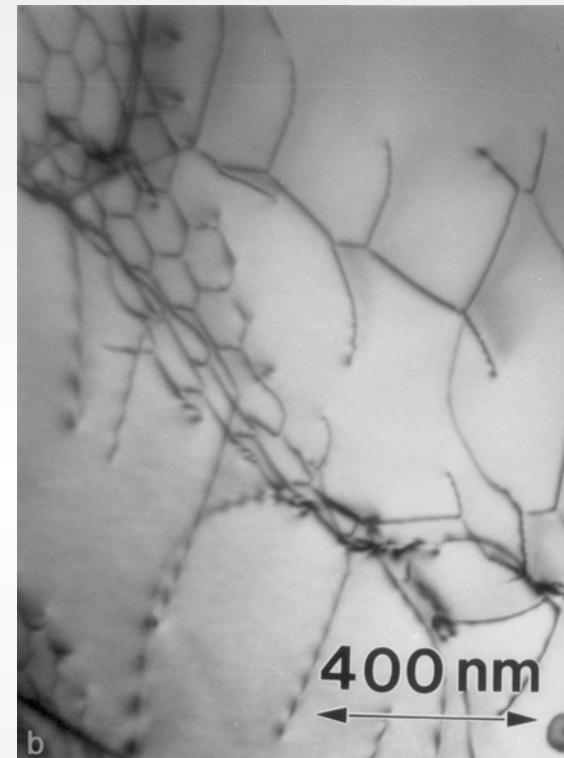


TiSi_2

TEM bright field images illustrating the dislocation structures in the as compacted samples



Ti_5Si_3



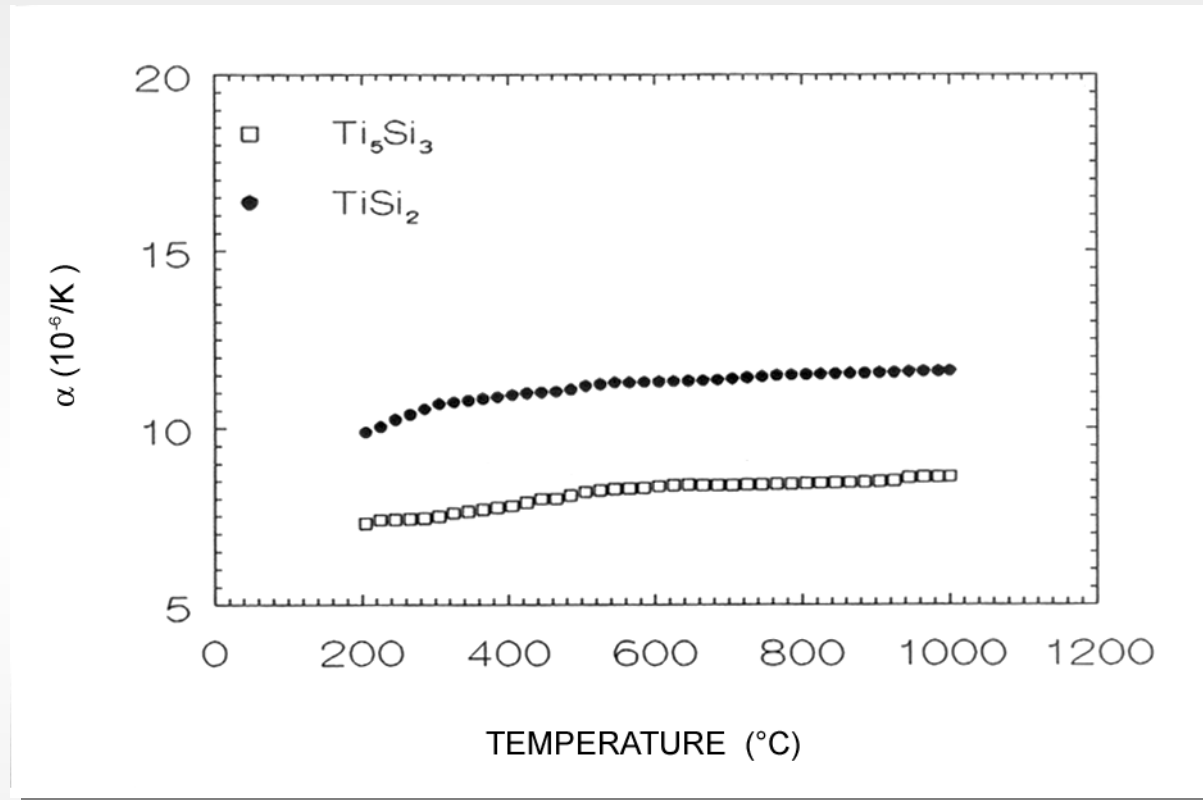
TiSi_2

TEM bright field images of creep deformed
samples tested at 1000 °C, strain rate $\dot{\epsilon} = 10^{-7} \text{s}^{-1}$

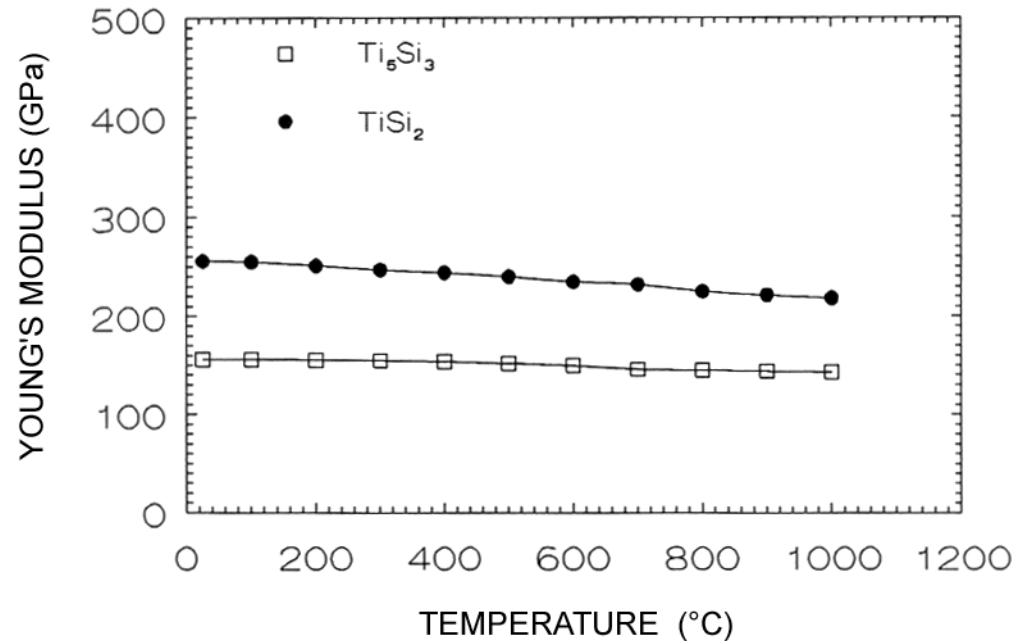


	bulk modulus K(GPa)	Young's modulus E(GPa)	shear modulus G(GPa)
Ti₅Si₃	110 ± 5	156 ± 8	61 ± 3
TiSi₂	125 ± 8	256 ± 10	103 ± 5

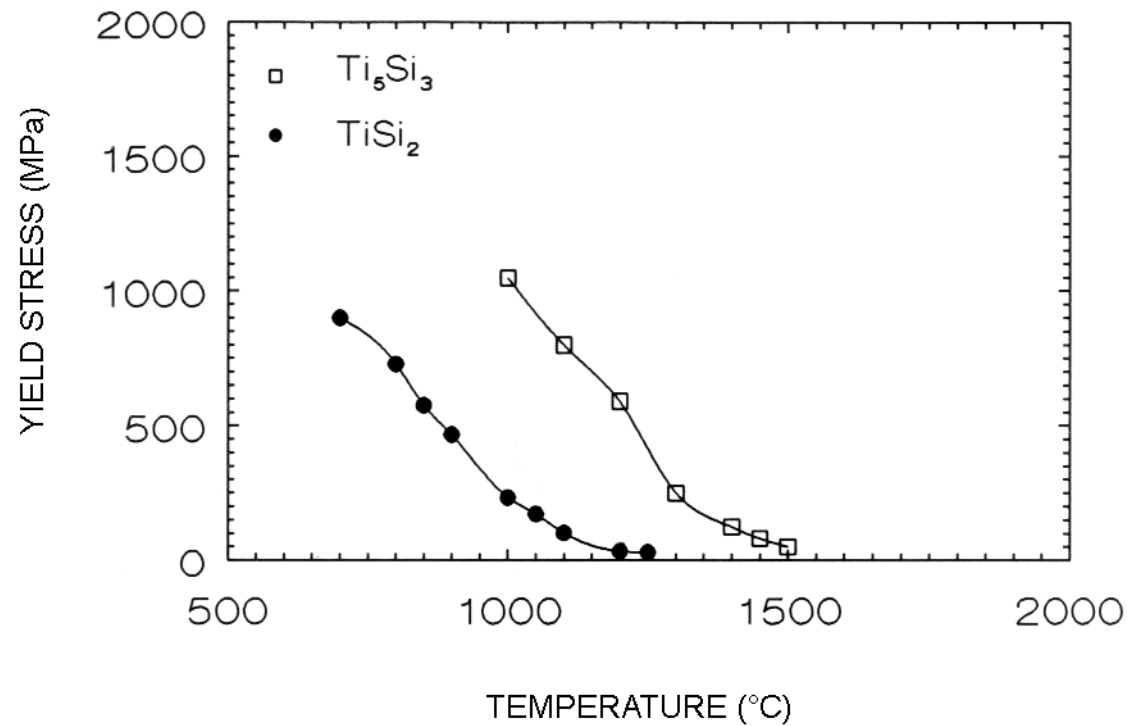
Elastic moduli K, E, G of Ti₅Si₃ and TiSi₂ at room temperature



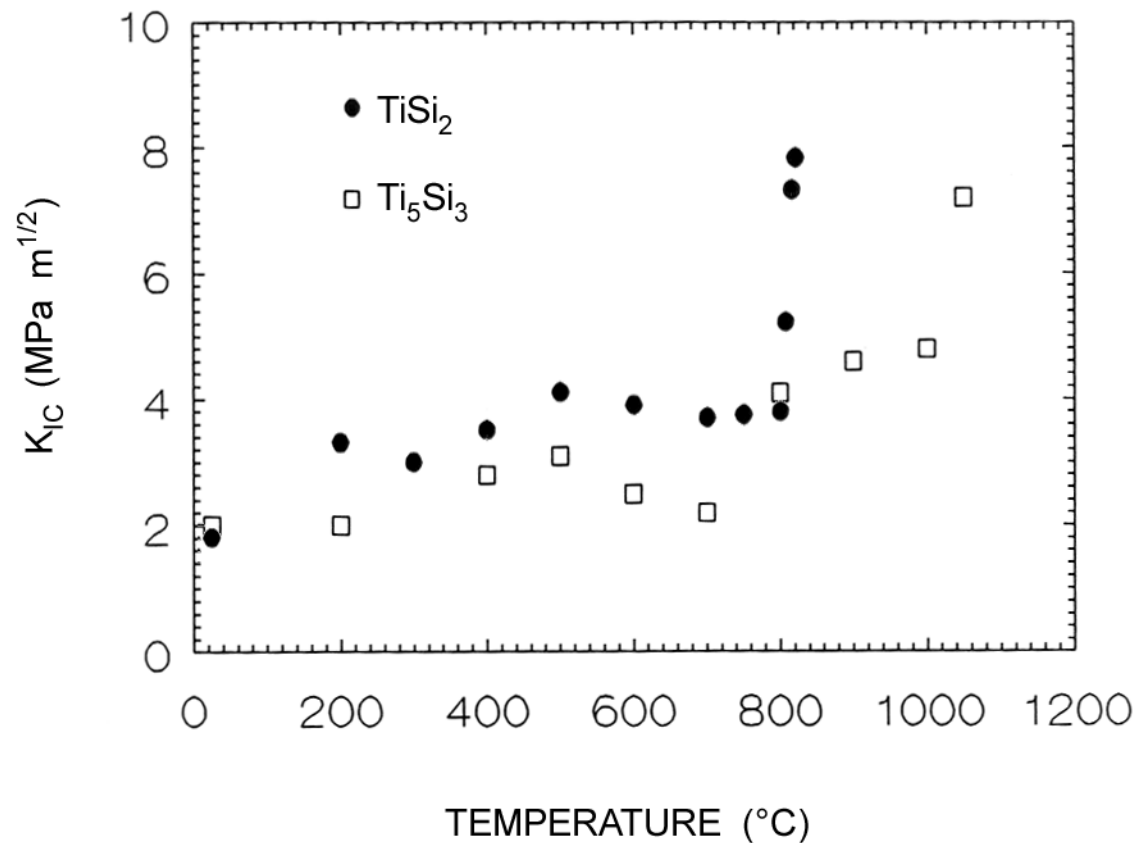
Temperature dependence of the thermal expansion coefficients of the monolithic Ti_5Si_3 and TiSi_2 compounds



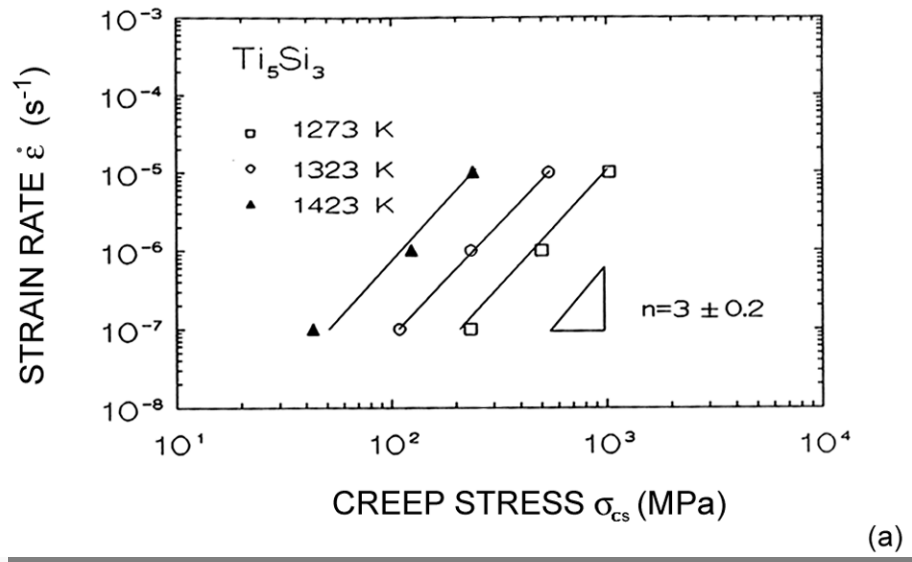
Young's moduli of the monolithic Ti_5Si_3 and TiSi_2 compounds as function of temperature



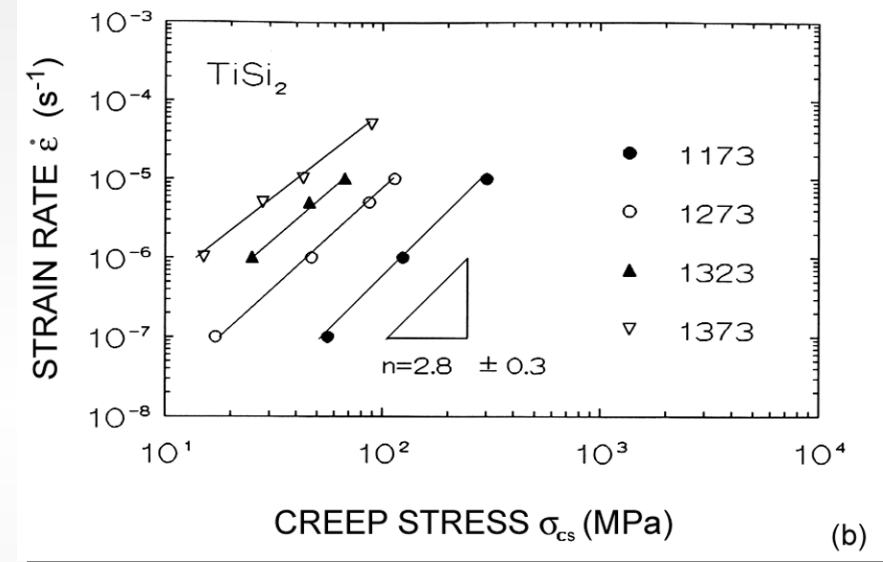
Yield stress vs. test temperature of the monolithic intermetallic Ti_5Si_3 and TiSi_2 compounds



Stress intensity factors of the intermetallic Ti_5Si_3 and TiSi_2 compounds as function of test temperature

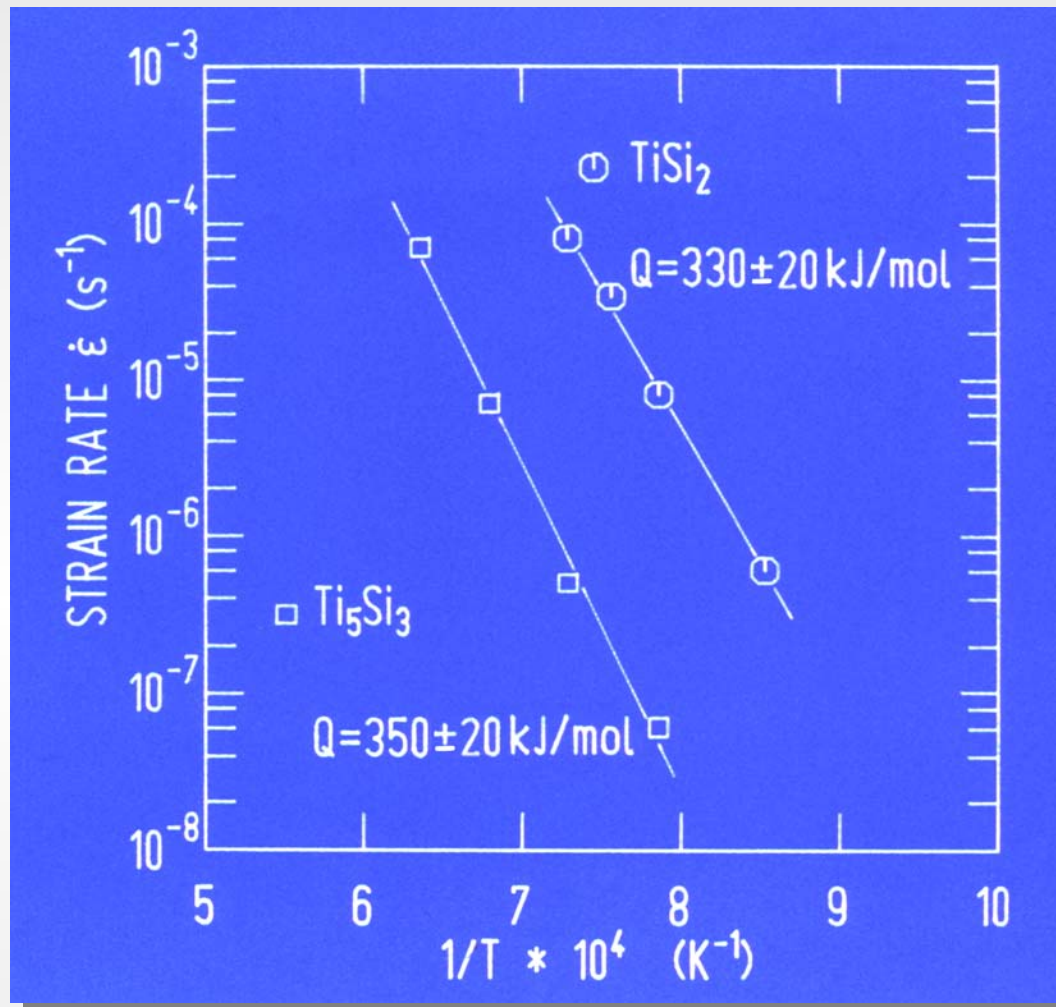


Ti₅Si₃

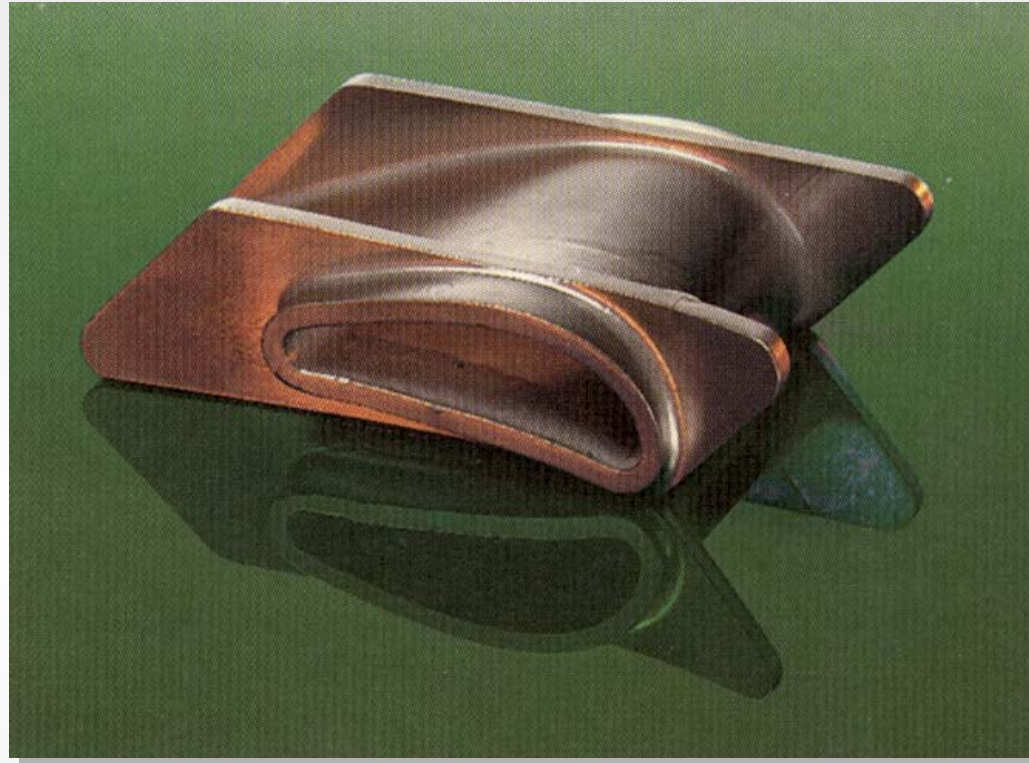


TiSi₂

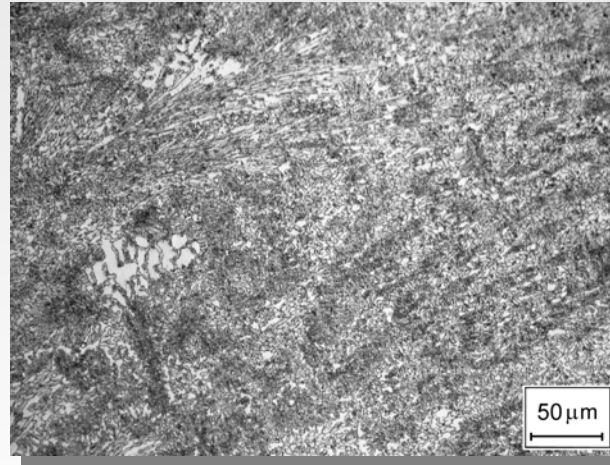
Stress exponent n derived from the slope of the $\log \dot{\epsilon}$ vs. $\log \sigma$ plot



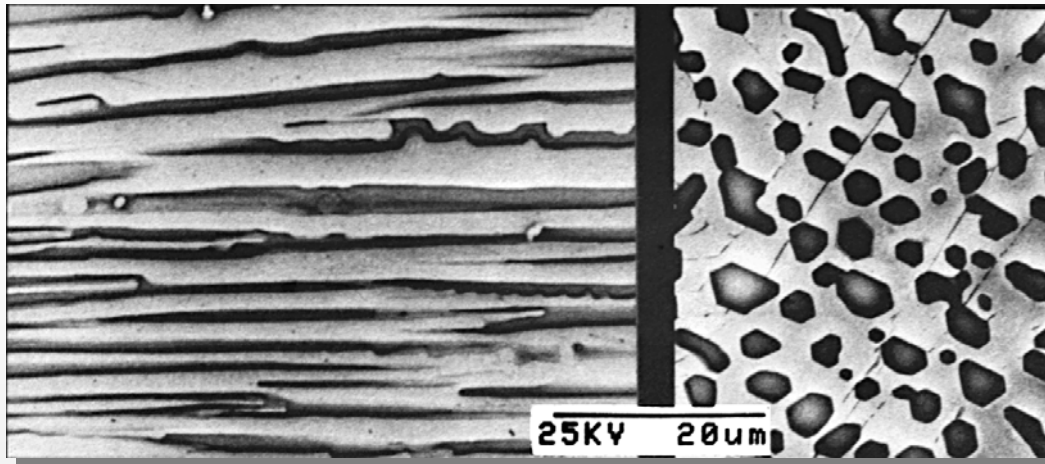
activation energies of Ti₅Si₃ and TiSi₂



**Powder metallurgically processed air foil of TiSi_2
tested in a combustion chamber at 1400 °C for 100 h**



(a)

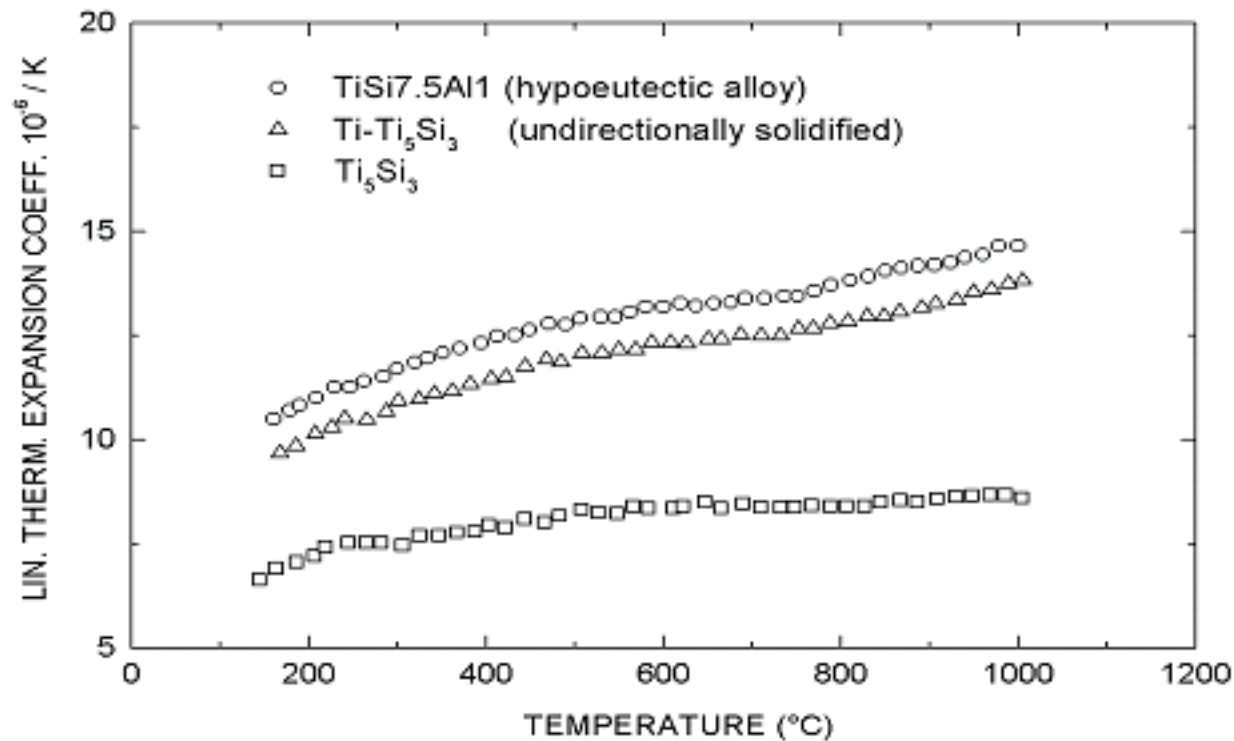


longitudinal section (b)

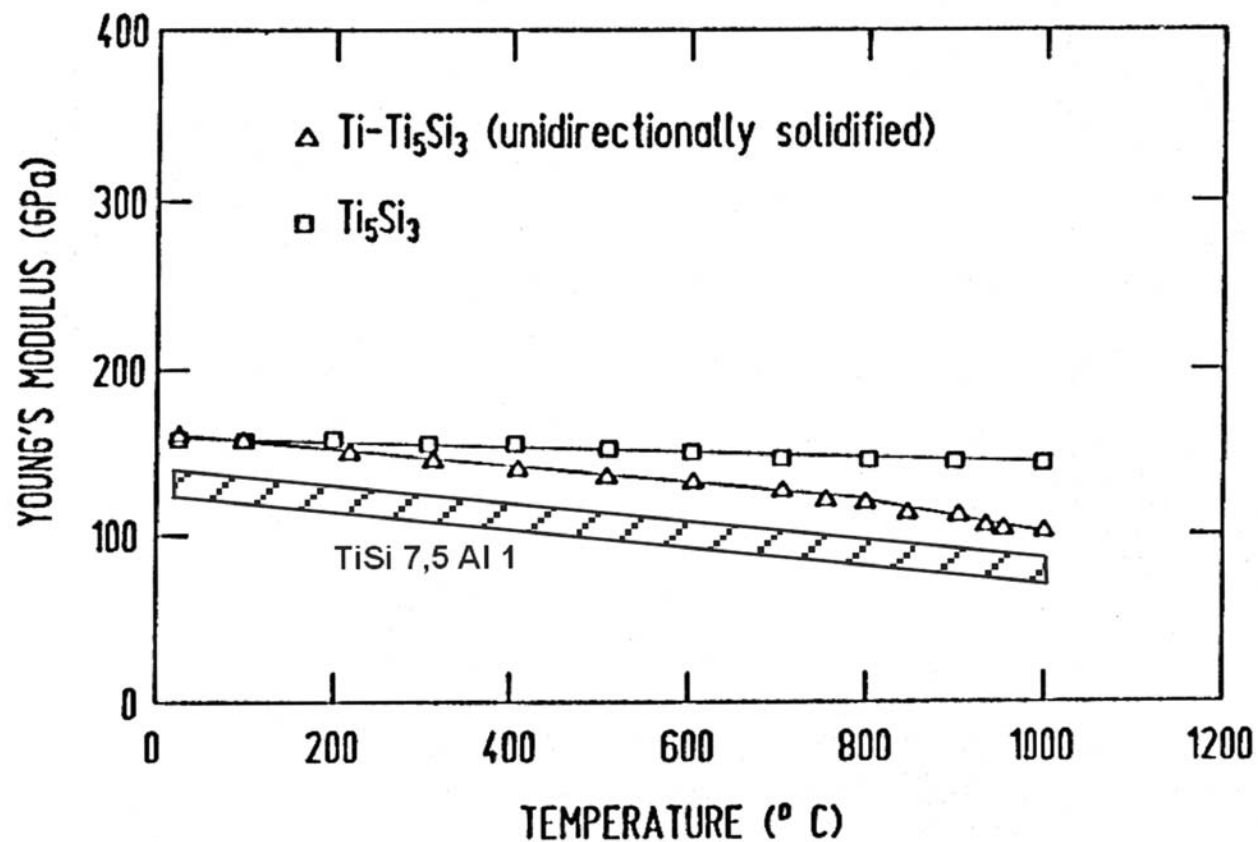
cross section (c)

Optical micrograph of the hypoeutectic Ti-7,5Si-Al1 illustrating primary solidified α -Ti solid solution grains (white areas) and fine grained eutectic (a).

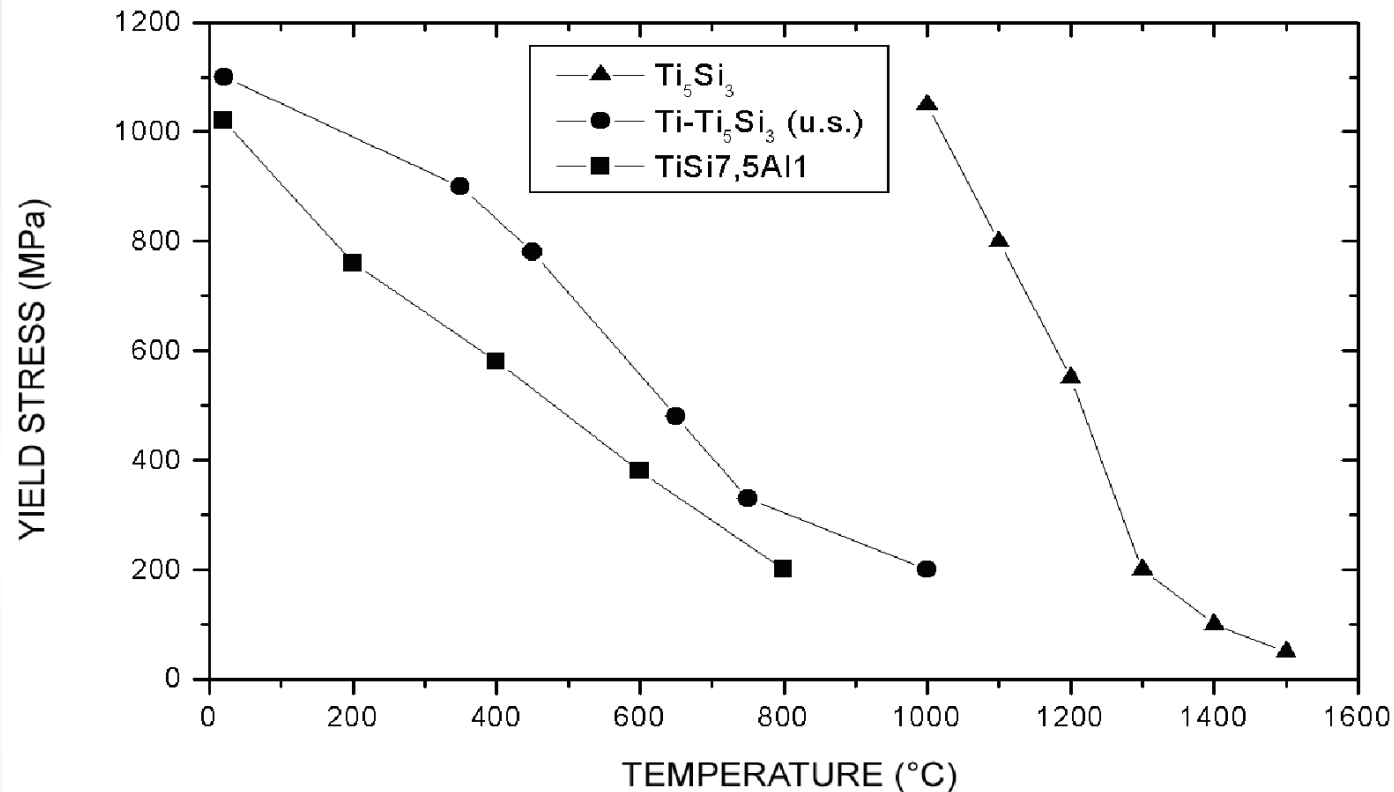
SEM micrographs showing the fibre structure of an unidirectionally solidified eutectic Ti-Ti₅Si₃ composite in longitudinal (b) and cross section (c)



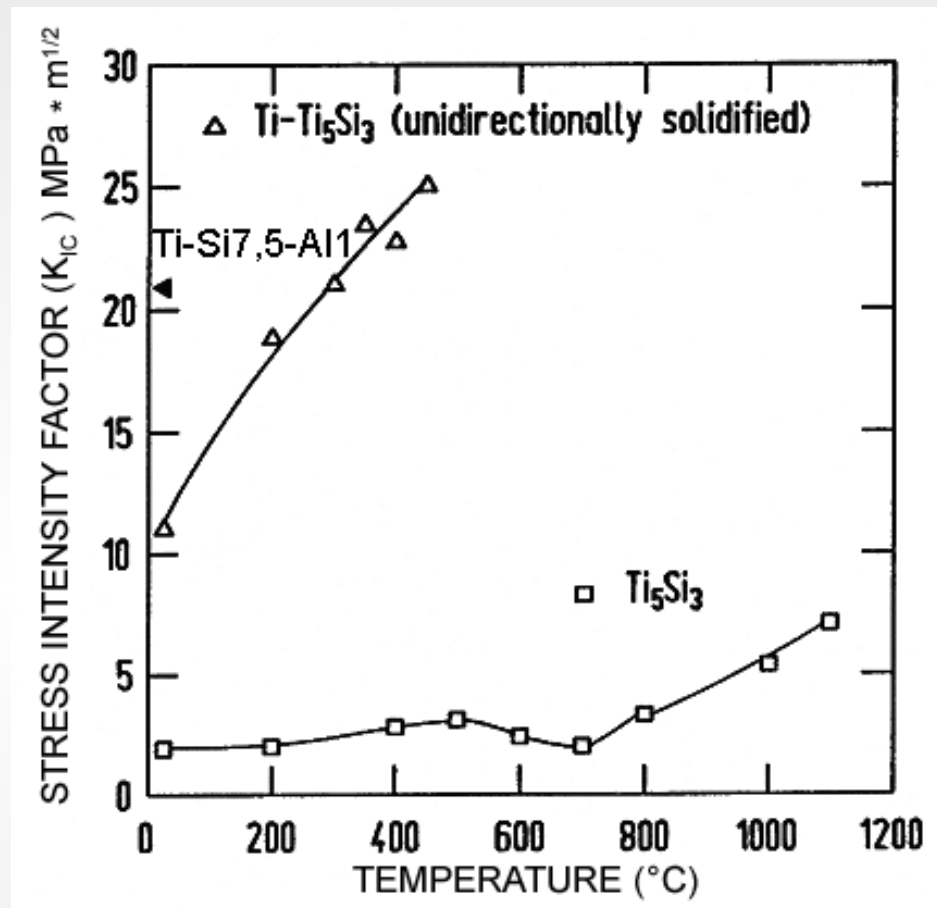
Temperature dependence of thermal expansion coefficients of Ti₅Si₃, the hypoeutectic Ti-Si7.5-Al1 alloy and the unidirectionally solidified eutectic Ti-Ti₅Si₃ composite



Young's moduli of the monolithic Ti_5Si_3 compound and of the hypoeutectic Ti-Si7.5-Al1 and the unidirectionally solidified eutectic $\text{Ti-Ti}_5\text{Si}_3$ alloy as function of the test temperature



Yield stress as function of temperature of the hypoeutectic Ti-Si7.5-Al1 alloy and the unidirectionally solidified eutectic Ti-Ti₅Si₃ composite. In comparison the yield stress curve of the Ti₅Si₃ compound is plotted in the diagram.



Stress intensity factors as function of temperature of the hypoeutectic Ti-Si_{7.5}-Al₁ alloys and of the directionally solidified Ti-Ti₅Si₃ composite in comparison to the Ti₅Si₃ compound



✦ Summary and Outlook

- ✦ Innovative refractory titanium silicides Ti_5Si_3 and TiSi_2 exhibit extraordinary physical and mechanical properties and show great potential applications as high-temperature light-weight materials for turbine air foils, heat shield tiles for combustion chambers and missile nozzles.
- ✦ The superior oxidation resistance is due to the formation of very stable SiO_2 surface layers
- ✦ The high elastic stiffness and hardness of these silicide compounds are caused by the strong covalent bonding of s-p and d-p electron interactions of the Si-Si and S-Ti atoms.
- ✦ The prominent high temperature strength, creep resistant and the restricted room temperature ductility are of intrinsic nature. The complex superlattice possess sessile superdislocations of large Burgers' vector of high energy.
- ✦ For improving the ductility and toughness of silicides micro- and macro alloying have been performed. Alpha titanium – Ti_5Si_3 composites exhibit improved room temperature ductility and combine the advantages of high flow stresses and elevated temperature strength.
- ✦ Hypoeutectic and directionally solidified eutectic $\alpha\text{-Ti} / \text{Ti}_5\text{Si}_3$ composites show considerable potential applications for axial compressor blades and outlet valves in internal combustion engines.